

PATENT ABSTRACTS OF JAPAN

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(71)Applicant : NISSAN MOTOR CO LTD

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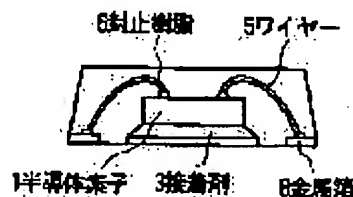
(72)Inventor : KIMURA TOSHIHIRO

(54) MANUFACTURING METHOD OF SEMICONDUCTOR ELEMENT

(57)Abstract:

PROBLEM TO BE SOLVED: To enable a high-density package like a chip package and facilitate the type change, irrespective of the production man-hours by fixing a semiconductor element to a metal foil with adhesives and electrically connecting the element to the foil through wires.

SOLUTION: A metal foil 8 is adhered to a base and etched leaving specified parts and a semiconductor element 1 is fixed to the foil 8, connected to it through wires 5 and sealed with a resin 6 and separated from the base to form a package. It is esp. essential to fix the element to the foil 8 through the adhesive 8 and electrically connected to it through the wires 5. Thus it is possible to provide a high-density package like a chip package and facilitate the type change, irrespective of the production man-hour.



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